

# 1S2074(H)

## Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0557-0300

(Previous: ADE-208-142B)

Rev.3.00

Mar 16, 2005

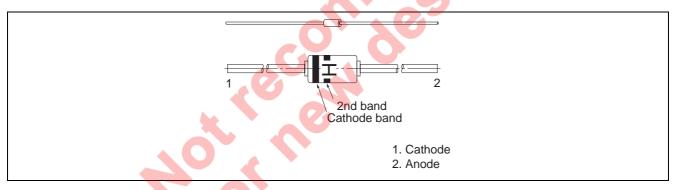
#### **Features**

- Low capacitance. (C = 3.0 pF max)
- Short reverse recovery time.  $(t_{rr} = 4.0 \text{ ns max})$
- High reliability with glass seal.

#### **Ordering Information**

Type No.	Cathode band	2nd band	Mark	Package Name	Package Code (Previous Code)
1S2074(H)	Green	White	Н	DO-35	GRZZ0002ZB-A (DO-35)

### **Pin Arrangement**



### **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Peak reverse voltage	$V_{RM}$	50	V
Reverse voltage	V <sub>R</sub>	45	V
Peak forward current	I <sub>FM</sub>	450	mA
Non-Repetitive peak forward surge current	I <sub>FSM</sub> *	600	mA
Average rectified current	I <sub>0</sub>	150	mA
Power dissipation	Pd	250	mW
Junction temperature	Tj	175	°C
Storage temperature	Tstg	-65 to +175	°C

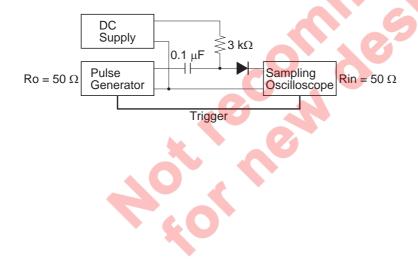
Note: Within 1s forward surge current.

#### **Electrical Characteristics**

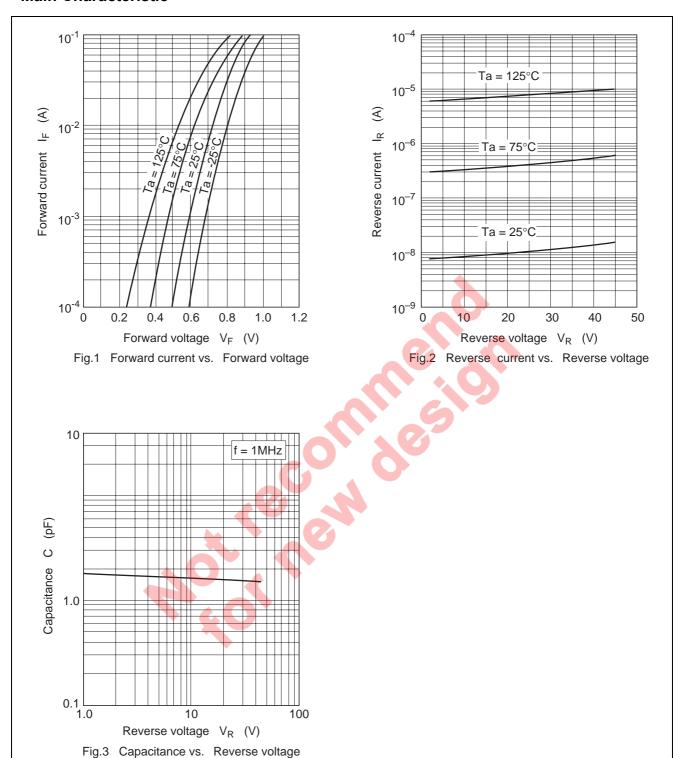
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	$V_{F}$	0.64	_	0.8	V	I <sub>F</sub> = 10 mA
Reverse current	$I_R$	_	_	100	nA	V <sub>R</sub> = 30 V
Capacitance	С	_	_	3.0	pF	V <sub>R</sub> = 1 V, f = 1 MHz
Reverse recovery time	t <sub>rr</sub> *	_		4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10 mA, Irr = 1 mA

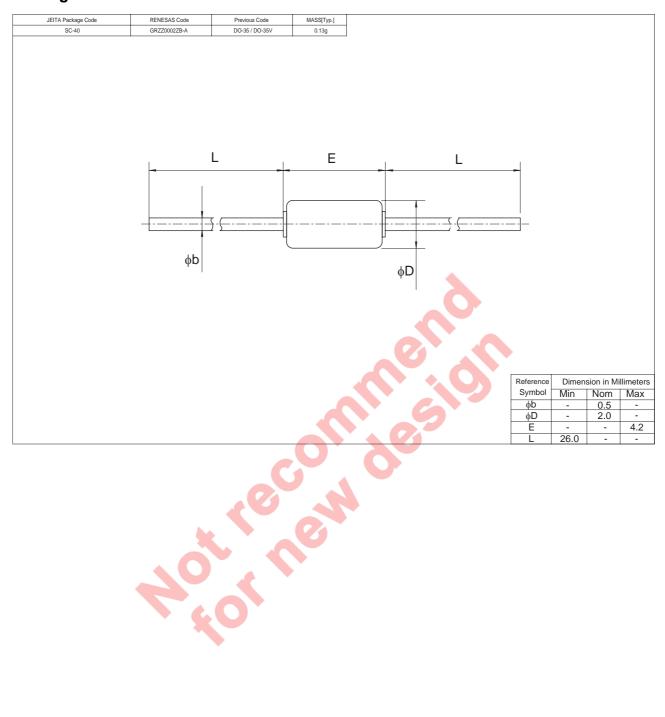
Note: Reverse recovery time test circuit



#### **Main Characteristic**



#### **Package Dimensions**



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